

10/511102

DT04 Rec'd PCT/PTO 14 OCT 2004

IN THE CLAIMS:

These claims will replace all prior versions of claims in the present application.

1. (Currently Amended) A thermosetting resin composition ~~eontainingcomprising~~:

(1) a metal salt of a ~~bisubstituteddisubstituted~~ phosphinic acid, and

(2) a resin having a dielectric constant of ~~equal to or less than 2.9 or less~~ at a frequency of 1 GHz or more.

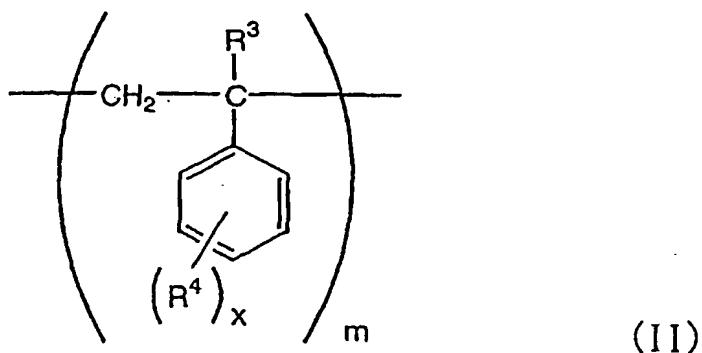
2. (Currently Amended) The thermosetting resin composition ~~as claimed in accordance to~~ claim 1, wherein the dielectric constant of the thermosetting resin composition is ~~equal to or less than 3.0 or less~~ at a frequency of 1 GHz or more.

3. (Currently Amended) The thermosetting resin composition ~~as claimed in accordance to~~ claim 1-~~or 2~~, which further ~~eontains_comprises~~ (3) a thermosetting nitrogen atom-containing resin.

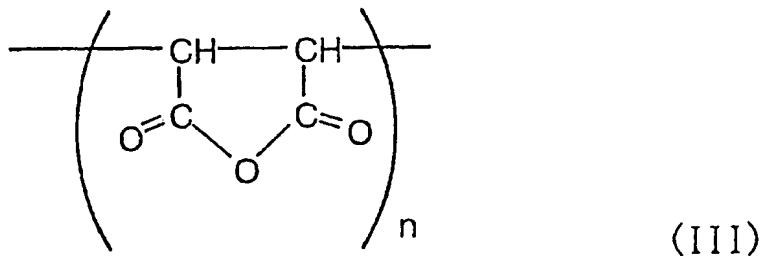
4. (Currently Amended) The thermosetting resin composition ~~as claimed in accordance to~~ claim 1-~~or 2~~, wherein the component (2) is ~~one or more_at least one~~ resin compositions selected from the group consisting of:

copolymer resin (2-1) ~~eontainingcomprising~~:

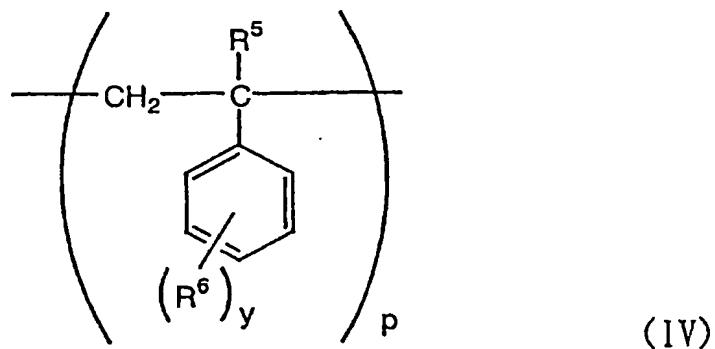
monomer unit (a) represented by formula (II):



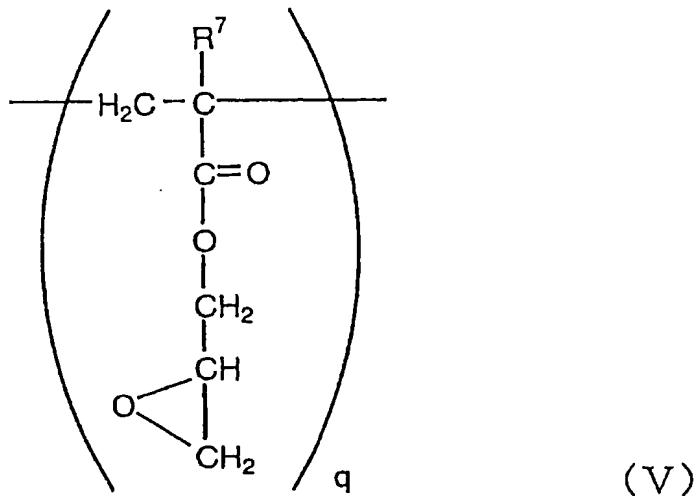
[wherein R^3 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^4 's are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; x is an integer of 0 to 3; and m is a natural number and represents representing the repeating number of a monomer unit in a copolymer], and monomer unit (b) represented by formula (III):



[wherein n is a natural number and represents representing the repeating number of a monomer unit in a copolymer];
copolymer resin (2-2) containing comprising:
monomer unit (c) represented by formula (IV):

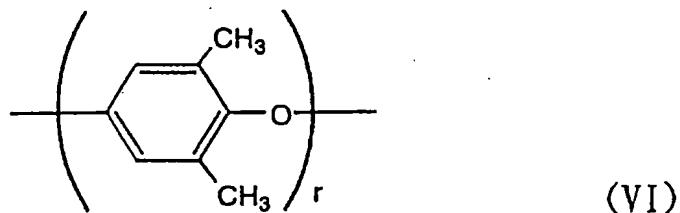


{wherein R⁵ is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R⁶'s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number and representsrepresenting the repeating number of a monomer unit in a copolymer}, and monomer unit (d) represented by formula (V):



{wherein R⁷ is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number and representsrepresenting the repeating number of a monomer unit in a copolymer}; and resin (2-3) containingcomprising:

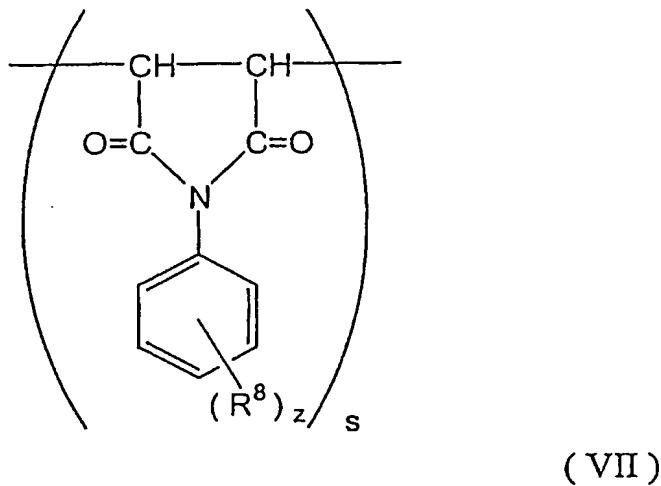
monomer unit (e) represented by formula (VI):



{wherein r is a natural number and representsrepresenting the repeating number of a monomer unit in a copolymer}.

5. (Currently Amended) The thermosetting resin composition as claimed in accordance to claim 4, wherein the copolymer resin (2-1) is a copolymer resin further containingcomprising:

monomer unit (f) represented by the following formula (VII):



(VII)

{wherein R⁸ is a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group, a hydroxyl group, a thiol group or a carboxyl group; z is an integer of 0 to 3; and s is a natural number and representsrepresenting the repeating number of a monomer unit in a copolymer}.

6. (Currently Amended) The thermosetting resin composition ~~as claimed in~~ according to claim 1-~~or~~2, which further ~~contains~~ comprises (4) an epoxy resin.

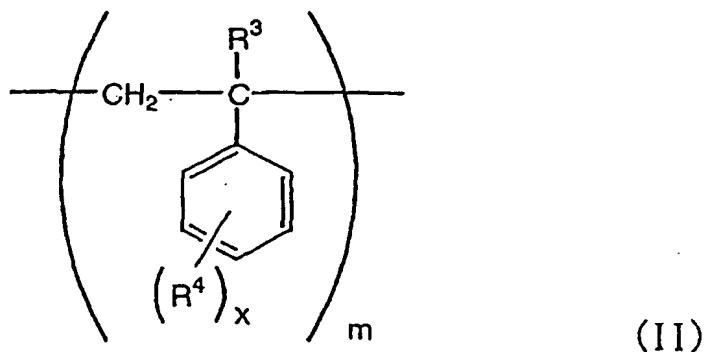
7. (Currently Amended) A prepreg using the thermosetting resin composition ~~claimed in~~ according to ~~any one of claims 1 to 6~~ claim 1.

8. (Currently Amended) A ~~laminated sheet~~laminated board obtained by using and laminate molding ~~using~~ the prepreg ~~claimed in~~ according to claim 7.

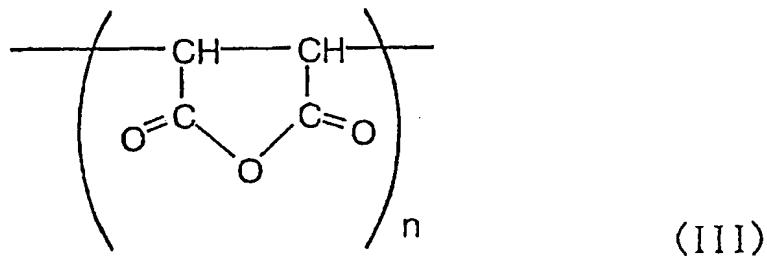
9. (Currently Amended) A thermosetting resin composition ~~eontaining~~ comprising a metal salt of a ~~bisubstituted~~disubstituted phosphinic acid, wherein a dielectric constant of the composition is ~~equal to or less than~~ 3.0 or less at a frequency of 1 GHz or more.

10. (New) The thermosetting resin composition according to claim 2, which further comprises (3) a thermosetting nitrogen atom-containing resin.

11. (New) The thermosetting resin composition according to claim 2, wherein the component (2) is at least one resin compositions selected from the group consisting of: copolymer resin (2-1) comprising:
monomer unit (a) represented by formula (II):



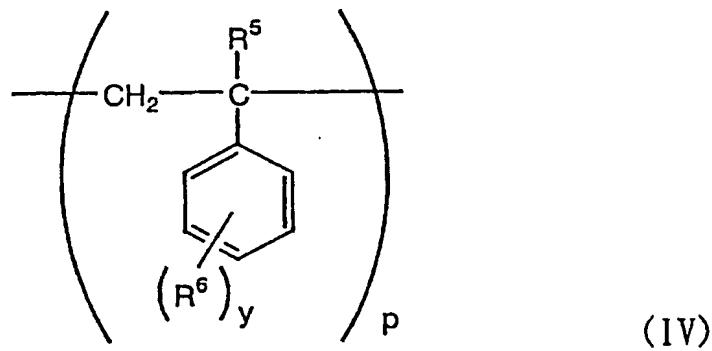
wherein R³ is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R⁴s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; x is an integer of 0 to 3; and m is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (b) represented by formula (III):



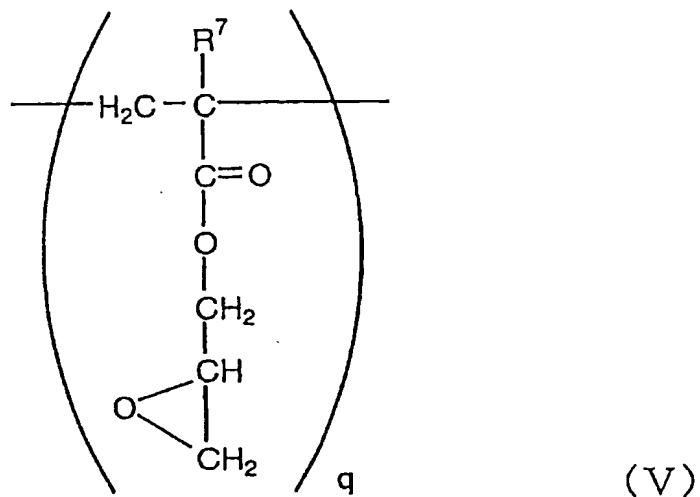
wherein n is a natural number representing the repeating number of a monomer unit in a copolymer;

copolymer resin (2-2) comprising:

monomer unit (c) represented by formula (IV):

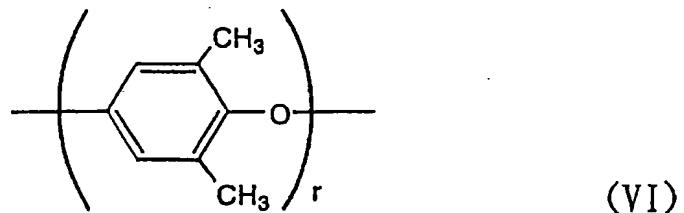


wherein R^5 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^6 's are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number and representing the repeating number of a monomer unit in a copolymer, and monomer unit (d) represented by formula (V):



wherein R^7 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number representing the repeating number of a monomer unit in a copolymer; and resin (2-3) comprising:

monomer unit (e) represented by formula (VI):



wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

12. (New) The thermosetting resin composition according to claim 2, which further comprises (4) an epoxy resin.